

acoustic microscopy

Wafer evaluation

delamination

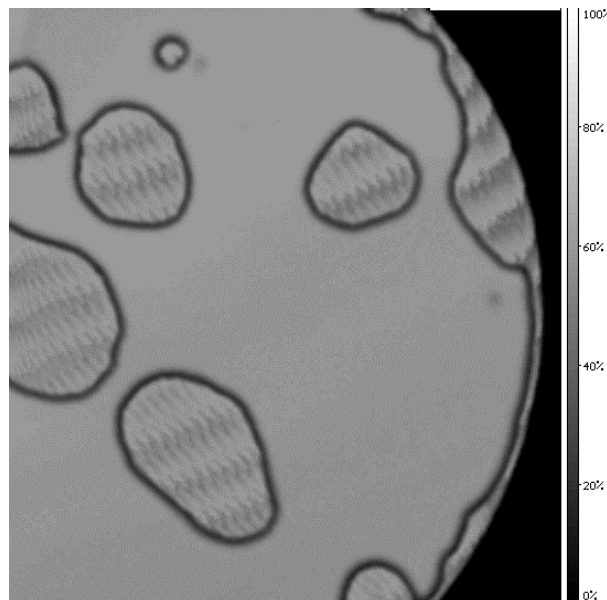
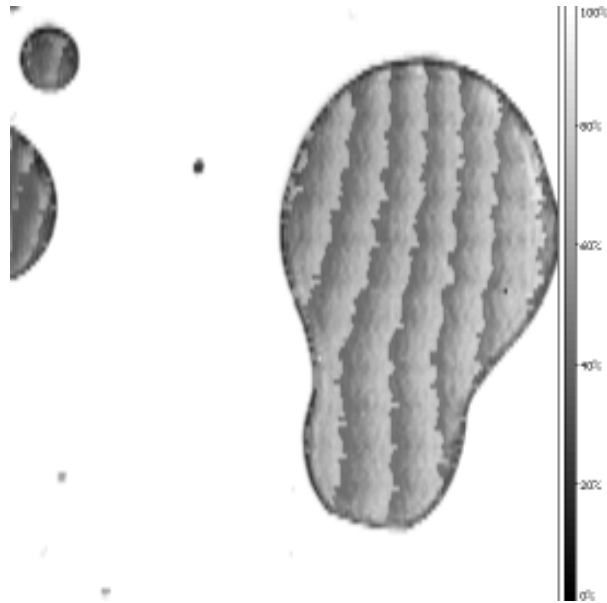


Fig. a and b: Delaminations are clearly visible in the interface 500 μ m below the surface of the Si-wafer